



STB70NFS03L

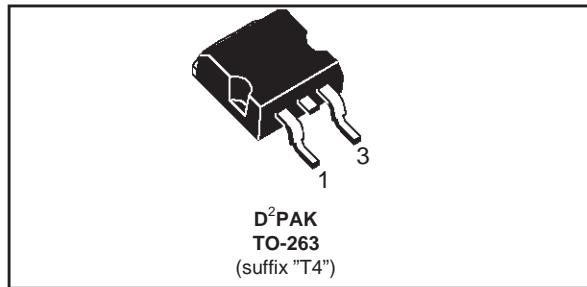
N - CHANNEL 30V - 0.008Ω - 70A D²PAK STripFETTM MOSFET PLUS SCHOTTKY RECTIFIER

PRELIMINARY DATA

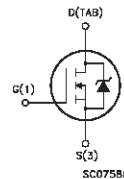
MAIN PRODUCT CHARACTERISTICS			
MOSFET	V _{DSS}	R _{D(on)}	I _D
	30V	<0.01Ω	70A
SCHOTTKY	I _{F(AV)}	V _{RRM}	V _{F(MAX)}
	3A	30V	0.51V

DESCRIPTION:

This product associates a Power MOSFET of the third generation of STMicroelectronics unique "Single Feature Size" strip-based process and a low drop Schottky diode. The transistor shows the best trade-off between on-resistance and gate charge. Used as low side in buck regulators, the product is the best solution in terms of conduction losses and space saving.



INTERNAL SCHEMATIC DIAGRAM



MOSFET ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{DS}	Drain-source Voltage (V _{GS} = 0)	30	V
V _{DGR}	Drain-gate Voltage (R _{GS} = 20 kΩ)	30	V
V _{GS}	Gate-source Voltage	± 22	V
I _D	Drain Current (continuous) at T _c = 25 °C	70	A
I _D	Drain Current (continuous) at T _c = 100 °C	50	A
I _{DM(•)}	Drain Current (pulsed)	280	A
P _{tot}	Total Dissipation at T _c = 25 °C	100	W
	Derating Factor	0.67	W/°C
T _{stg}	Storage Temperature	-65 to 175	°C
T _j	Max. Operating Junction Temperature	175	°C

(•) Pulse width limited by safe operating area

SCHOTTKY ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{RRM}	Repetitive Peak Reverse Voltage	30	V
I _{F(RMS)}	RMS Forward Current	20	A
I _{F(AV)}	Average Forward Current	T _L =125 °C δ=0.5	A
I _{FSM}	Surge Non Repetitive Forward Current	tp= 10 ms Sinusoidal	A
dv/dt	Critical Rate Of Rise Of Reverse Voltage	10000	V/μs

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THERMAL DATA

R _{thj-case}	Thermal Resistance Junction-case	Max	1.5	°C/W
R _{thj-amb}	Thermal Resistance Junction-ambient	Max	62.5	°C/W
T _I	Maximum Lead Temperature For Soldering Purpose		175	°C

ELECTRICAL CHARACTERISTICS (T_{case} = 25 °C unless otherwise specified)

OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V _{(BR)DSS}	Drain-source Breakdown Voltage	I _D = 250 μA V _{GS} = 0	30			V
I _{DSS}	Zero Gate Voltage Drain Current (V _{GS} = 0)	V _{DS} = Max Rating V _{DS} = Max Rating T _c = 125 °C			1 10	μA μA
I _{GSS}	Gate-body Leakage Current (V _{DS} = 0)	V _{GS} = ± 20 V			± 100	nA

ON (*)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} I _D = 250 μA	1			V
R _{D(on)}	Static Drain-source On Resistance	V _{GS} = 10 V I _D = 35 A V _{GS} = 5 V I _D = 18 A		0.008 0.015	0.01 0.018	Ω Ω
I _{D(on)}	On State Drain Current	V _{DS} > I _{D(on)} × R _{D(on)max} V _{GS} = 10 V	70			A

DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
g _{fs} (*)	Forward Transconductance	V _{DS} > I _{D(on)} × R _{D(on)max} I _D = 35 A		40		S
C _{iss} C _{oss} C _{rss}	Input Capacitance Output Capacitance Reverse Transfer Capacitance	V _{DS} = 25 V f = 1 MHz V _{GS} = 0		1470 490 110		pF pF pF

ELECTRICAL CHARACTERISTICS (continued)

SWITCHING ON

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$ t_r	Turn-on Delay Time Rise Time	$V_{DD} = 15 \text{ V}$ $I_D = 35 \text{ A}$ $R_G = 4.7 \Omega$ $V_{GS} = 10 \text{ V}$ (Resistive Load, see fig. 3)		20 350		ns ns
Q_g Q_{gs} Q_{gd}	Total Gate Charge Gate-Source Charge Gate-Drain Charge	$V_{DD} = 24 \text{ V}$ $I_D = 46 \text{ A}$ $V_{GS} = 10 \text{ V}$		35 5 10	45	nC nC nC

SWITCHING OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(off)}$ t_f	Off-voltage Rise Time Fall Time	$V_{DD} = 24 \text{ V}$ $I_D = 35 \text{ A}$ $R_G = 4.7 \Omega$ $V_{GS} = 10 \text{ V}$ (Resistive Load, see fig. 3)		35 65		ns ns

SOURCE DRAIN DIODE

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I_{SD} $I_{SDM}(\bullet)$	Source-drain Current Source-drain Current (pulsed)				70 280	A A
$V_{SD} (\ast)$	Forward On Voltage	$I_{SD} = 70 \text{ A}$ $V_{GS} = 0$			1.5	V
t_{rr} Q_{rr} I_{RRM}	Reverse Recovery Reverse Recovery Reverse Recovery	$I_{SD} = 70 \text{ A}$ $di/dt = 100 \text{ A}/\mu\text{s}$ $V_{DD} = 15 \text{ V}$ $T_j = 150 \text{ }^\circ\text{C}$ (see test circuit, figure 5)		70 105 2.4		ns nC A

(*) Pulsed: Pulse duration = 300 μs , duty cycle 1.5 %

(\bullet) Pulse width limited by safe operating area

SCHOTTKY STATIC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$I_R(\ast)$	Reversed Leakage Current	$T_J = 25 \text{ }^\circ\text{C}$ $V_R = 30 \text{ V}$ $T_J = 125 \text{ }^\circ\text{C}$ $V_R = 30 \text{ V}$		0.03	0.2 100	mA mA
$V_F(\ast)$	Forward Voltage drop	$T_J = 25 \text{ }^\circ\text{C}$ $I_F = 3 \text{ A}$ $T_J = 125 \text{ }^\circ\text{C}$ $I_F = 3 \text{ A}$		0.38	0.51 0.46	V V

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Fig. 1: Unclamped Inductive Load Test Circuit



Fig. 2: Unclamped Inductive Waveform

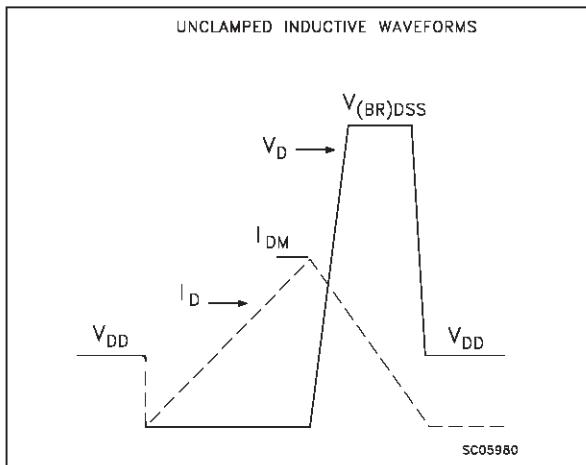


Fig. 3: Switching Times Test Circuits For Resistive Load



Fig. 4: Gate Charge test Circuit

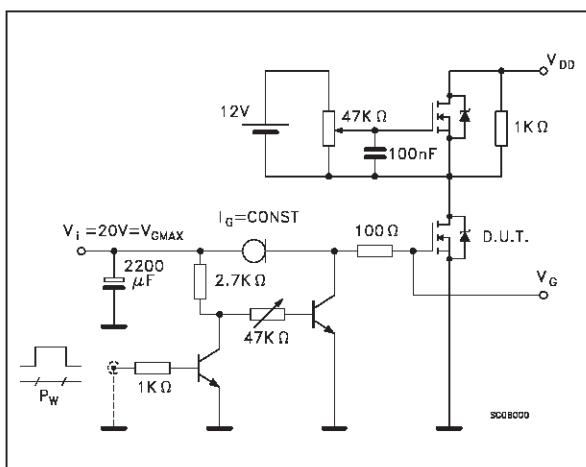
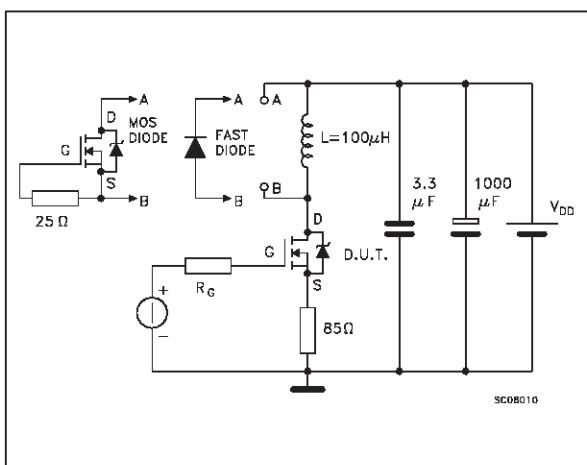
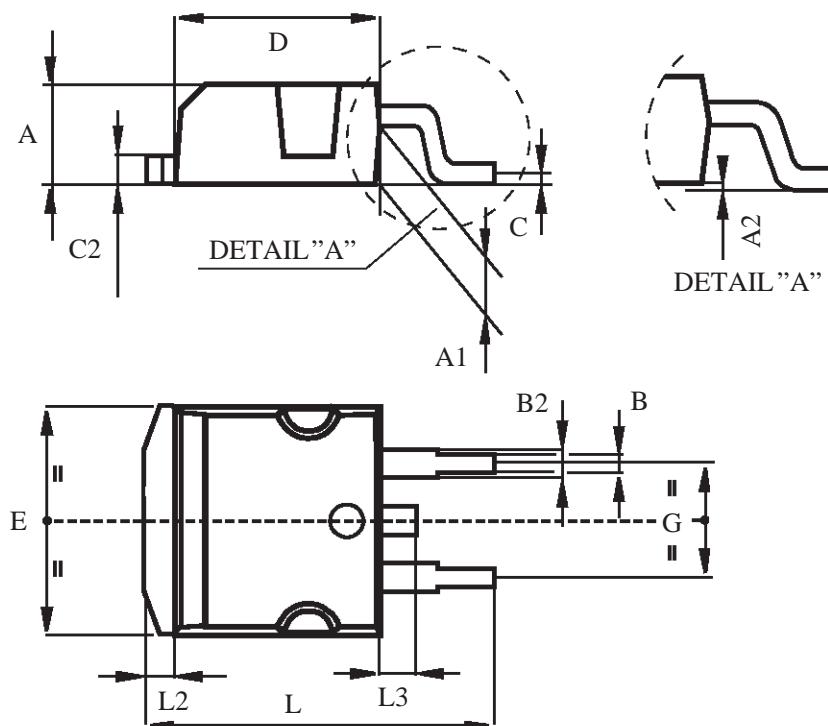


Fig. 5: Test Circuit For Inductive Load Switching And Diode Recovery Times



TO-263 (D²PAK) MECHANICAL DATA

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	4.4		4.6	0.173		0.181
A1	2.49		2.69	0.098		0.106
B	0.7		0.93	0.027		0.036
B2	1.14		1.7	0.044		0.067
C	0.45		0.6	0.017		0.023
C2	1.21		1.36	0.047		0.053
D	8.95		9.35	0.352		0.368
E	10		10.4	0.393		0.409
G	4.88		5.28	0.192		0.208
L	15		15.85	0.590		0.624
L2	1.27		1.4	0.050		0.055
L3	1.4		1.75	0.055		0.068



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